

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT3496713

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
NARESH KUMAR PENTA	11/06/2013
LEE MELBOURNE COOK	11/06/2013
NAOKO KAWAI	12/11/2013
HIROYUKI NAKANO	12/06/2013
SHINICHI HABA	12/11/2013
YOSHIHARU OTA	12/12/2013
TAKAYUKI MATSUSHITA	12/11/2013
MASASHI TERAMOTO	12/11/2013
SAKIKO NAKASHIMA	12/11/2013
TOMOYUKI TODA	12/13/2013
KOICHI YOSHIDA	12/13/2013
YASUYUKI ITAI	12/11/2013
RECEIVING PARTY DATA	
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14039390
CORRESPONDENCE DATA	
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PATENT	

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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ATTORNEY DOCKET NUMBER:	75392
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NAME OF SUBMITTER:	PATRICIA CONNELL
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SIGNATURE:	/patricia connell/
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DATE SIGNED:	08/25/2015
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Total Attachments: 3

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ASSIGNMENT OF PATENT APPLICATION

We/I, the undersigned

Naresh Kumar Penta and Lee Melbourne Cook

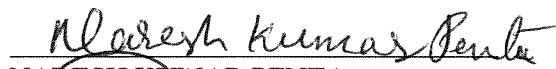
Hereby declare that

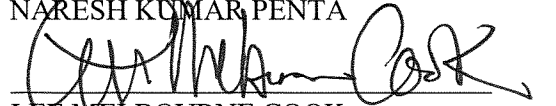
We/I are true and first inventor(s) of an invention relating to

**A CHEMICAL MECHANICAL POLISHING COMPOSITION FOR POLISHING SILICON WAFERS
AND RELATED METHODS**

which is disclosed in an application for Letters Patent in the United States of America, executed the 6th day of November, 2013(Case No. 75392); and, for valuable consideration, the receipt and adequacy of which is hereby acknowledged and in fulfillment of our pre-existing obligation of assignment, we hereby sell, assign and transfer unto Rohm and Haas Electronic Materials CMP Holdings, Inc., a corporation organized and existing under the laws of the State of Delaware in the United States of America and having its mailing address at 451 Bellevue Road, Newark, Delaware, hereinafter referred to as the assignee, the entire right, title, and interest in and to the aforesaid application for Letters Patent, including any priority rights derived from the aforesaid application for Letters Patent by virtue of the International Convention for the Protection of Industrial Property for any and all member countries of the aforesaid International Convention, and the entire right, title and interest in and to any and all our inventions, whether joint or sole, disclosed in the aforesaid application for Letters Patent, and in and to any and all applications for letters Patent for any such inventions in any country whatsoever, and in and to any and all patents for any such inventions in any country whatsoever, with the sole right to file such applications in its name or ours, including the sole right to file such applications under the aforesaid International Convention, together with the sole right to have said patents granted in its name or ours and to enforce said patents and to sue for and recover profits and damages for any and all infringements thereof, and hereby agree, whenever requested, to communicate to us respecting said inventions, to testify in any legal proceeding, to execute all applications, papers, or instruments necessary or required by said assignee, its successors, assigns, and legal representatives to carry into effect any of the provisions of this instrument, and generally to do everything possible to aid said assignee, its successors, assigns and legal representatives to obtain and enforce proper patent protection for said inventions in any and all countries.

IN WITNESS WHEREOF, We have hereunto signed our names on the day and year set forth below.



NARESH KUMAR PENTA


LEE MELBOURNE COOK

11/06/2013

DATE
11/06/2013

DATE

ASSIGNMENT OF PATENT APPLICATION

We/I, the undersigned

Yasuyuki Itai, Naoko Kawai, Hiroyuki Nakano, Shinichi Haba, Yoshiharu Ota, Takayuki Matsushita, Masashi Teramoto, Sakiko Nakashima, Tomoyuki Toda, and Koichi Yoshida

Hereby declare that

We/I are true and first inventor(s) of an invention relating to

A CHEMICAL MECHANICAL POLISHING COMPOSITION FOR POLISHING SILICON WAFERS AND RELATED METHODS

which is disclosed in an application for Letters Patent in the United States of America, executed the 6th, 11th & 13th day of December, 2013(Case No. 75392); and, for valuable consideration, the receipt and adequacy of which is hereby acknowledged and in fulfillment of our pre-existing obligation of assignment, we hereby sell, assign and transfer unto Nitta Haas Incorporated, a corporation organized and existing under the laws of Japan and having its mailing address at 4-4-26 Sakuragawa, Naniwa-Ku, Osaka-Shi, Osaka, 556-0022, Japan, hereinafter referred to as the assignee, the entire right, title, and interest in and to the aforesaid application for Letters Patent, including any priority rights derived from the aforesaid application for Letters Patent by virtue of the International Convention for the Protection of Industrial Property for any and all member countries of the aforesaid International Convention, and the entire right, title and interest in and to any and all our inventions, whether joint or sole, disclosed in the aforesaid application for Letters Patent, and in and to any and all applications for letters Patent for any such inventions in any country whatsoever, and in and to any and all patents for any such inventions in any country whatsoever, with the sole right to file such applications in its name or ours, including the sole right to file such applications under the aforesaid International Convention, together with the sole right to have said patents granted in its name or ours and to enforce said patents and to sue for and recover profits and damages for any and all infringements thereof, and hereby agree, whenever requested, to communicate to us respecting said inventions, to testify in any legal proceeding, to execute all applications, papers, or instruments necessary or required by said assignee, its successors, assigns, and legal representatives to carry into effect any of the provisions of this instrument, and generally to do everything possible to aid said assignee, its successors, assigns and legal representatives to obtain and enforce proper patent protection for said inventions in any and all countries.

IN WITNESS WHEREOF, We have hereunto signed our names on the day and year set forth below.

板井 康行
Yasuyuki Itai

11. 12. 2013
DATE

河井 奈緒子
Naoko Kawai

11. 12. 2013
DATE

中野 裕之

Hiroyuki Nakano

06/12/2013

DATE

羽場 真一

Shinichi Haba

11.12.2013

DATE

太田 慶治

Yoshiharu Ota

12.12.2013

DATE

松下 隆幸

Takayuki Matsushita

11.12.2013

DATE

寺本 匠志

Masashi Teramoto

11.12.2013

DATE

中島 咲子

Sakiko Nakashima

11.12.2013

DATE

戸田 智之

Tomoyuki Toda

13.12.2013

DATE

吉田 光一

Koichi Yoshida

13.12.2013

DATE